

## Absolute Maximum Ratings @ 25°C

| Parameter                            | Ratings     | Units            |
|--------------------------------------|-------------|------------------|
| Blocking Voltage                     | 60          | V <sub>P</sub>   |
| Reverse Input Voltage                | 5           | V                |
| Input Control Current                | 50          | mA               |
| Peak (10ms)                          | 1           | A                |
| Input Power Dissipation <sup>1</sup> | 70          | mW               |
| Total Power Dissipation <sup>2</sup> | 400         | mW               |
| Isolation Voltage, Input to Output   | 1500        | V <sub>rms</sub> |
| Operational Temperature, Ambient     | -40 to +85  | °C               |
| Storage Temperature                  | -40 to +125 | °C               |

<sup>1</sup> Derate linearly 1.33 mW / °C

<sup>2</sup> Derate output power linearly 3.33 mW / °C

*Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.*

*Typical values are characteristic of the device at +25°C, and are the result of engineering evaluations. They are provided for information purposes only, and are not part of the manufacturing testing requirements.*

## Electrical Characteristics @ 25°C

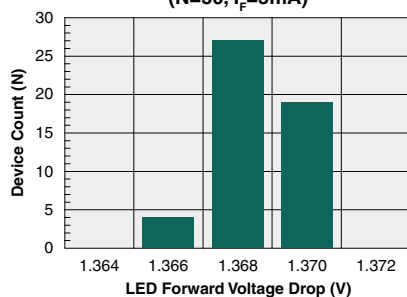
| Parameter                                      | Conditions                                       | Symbol            | Min              | Typ  | Max | Units            |
|------------------------------------------------|--------------------------------------------------|-------------------|------------------|------|-----|------------------|
| Output Characteristics                         |                                                  |                   |                  |      |     |                  |
| Blocking Voltage                               | I <sub>L</sub> =1μA                              | V <sub>DRM</sub>  | 60               | -    | -   | V                |
| Load Current                                   | I <sub>F</sub> =2mA                              | I <sub>L</sub>    | -                | -    | 750 | mA <sub>DC</sub> |
| Continuous                                     |                                                  |                   | -                | -    | 1   | A                |
| Continuous, AC Peak                            |                                                  | t ≤ 10ms          | I <sub>LPK</sub> | -    | -   | 3                |
| On-Resistance <sup>1</sup>                     | I <sub>L</sub> =750mA                            | R <sub>ON</sub>   | -                | 0.35 | 0.6 | Ω                |
| Off-State Leakage Current                      | V <sub>L</sub> =60V <sub>P</sub>                 | I <sub>LEAK</sub> | -                | -    | 1   | μA               |
| Switching Speeds                               | I <sub>F</sub> =5mA, V <sub>L</sub> =10V         | t <sub>on</sub>   | -                | 0.4  | 3   | ms               |
| Turn-On                                        |                                                  | t <sub>off</sub>  | -                | 0.4  | 3   | ms               |
| Turn-Off                                       | I <sub>F</sub> =0mA, V <sub>L</sub> =50V, f=1MHz | C <sub>OUT</sub>  | -                | 60   | -   | pF               |
| Input Characteristics                          |                                                  |                   |                  |      |     |                  |
| Input Control Current to Activate <sup>2</sup> | I <sub>L</sub> =750mA                            | I <sub>F</sub>    | -                | 0.15 | 2   | mA               |
| Input Control Current to Deactivate            | -                                                | I <sub>F</sub>    | 0.1              | 0.14 | -   | mA               |
| Input Voltage Drop                             | I <sub>F</sub> =5mA                              | V <sub>F</sub>    | 0.9              | 1.36 | 1.5 | V                |
| Reverse Input Current                          | V <sub>R</sub> =5V                               | I <sub>R</sub>    | -                | -    | 10  | μA               |
| Common Characteristics                         |                                                  |                   |                  |      |     |                  |
| Capacitance, Input to Output                   | V <sub>IO</sub> =0V, f=1MHz                      | C <sub>IO</sub>   | -                | 1    | -   | pF               |

<sup>1</sup> Measurement taken within 1 second of on-time.

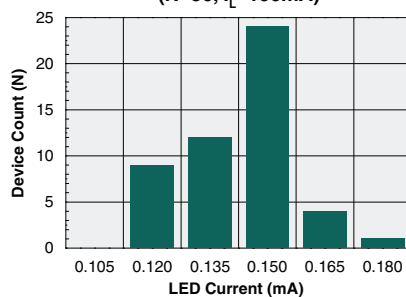
<sup>2</sup> For applications requiring high temperature operation (greater than 60°C) a minimum LED drive current of 4mA is recommended.

# PERFORMANCE DATA\*

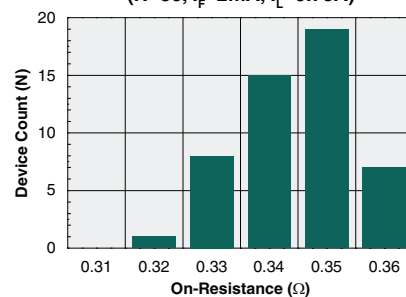
Typical LED Forward Voltage Drop  
(N=50,  $I_F=5\text{mA}$ )



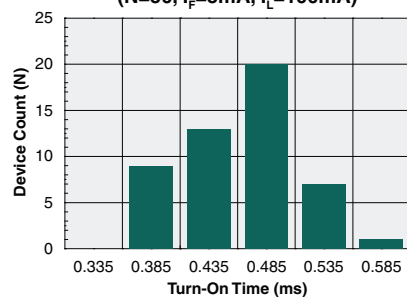
Typical  $I_F$  for Switch Operation  
(N=50,  $I_L=100\text{mA}$ )



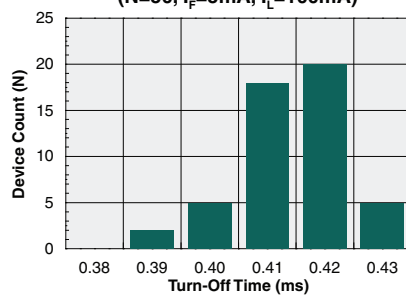
Typical On-Resistance Distribution  
(N=50,  $I_F=2\text{mA}$ ,  $I_L=0.75\text{A}$ )



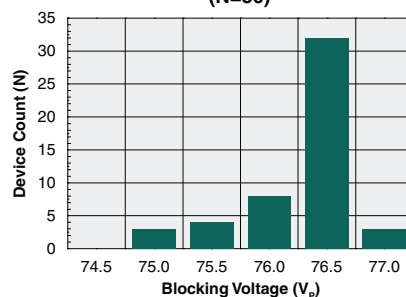
Typical Turn-On Time Distribution  
(N=50,  $I_F=5\text{mA}$ ,  $I_L=100\text{mA}$ )



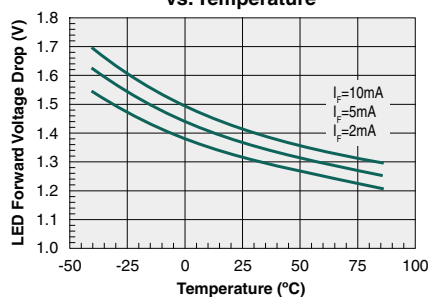
Typical Turn-Off Time Distribution  
(N=50,  $I_F=5\text{mA}$ ,  $I_L=100\text{mA}$ )



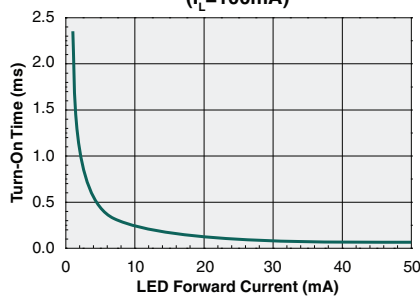
Typical Blocking Voltage Distribution  
(N=50)



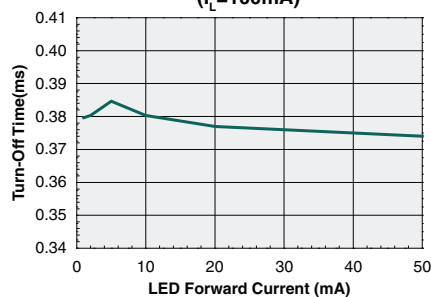
Typical LED Forward Voltage Drop  
vs. Temperature



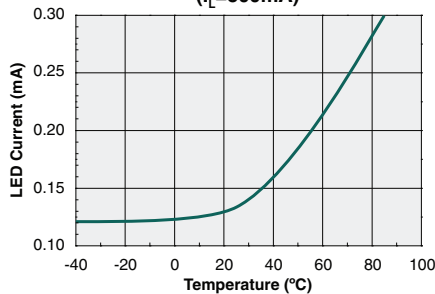
Typical Turn-On Time  
vs. LED Forward Current  
( $I_L=100\text{mA}$ )



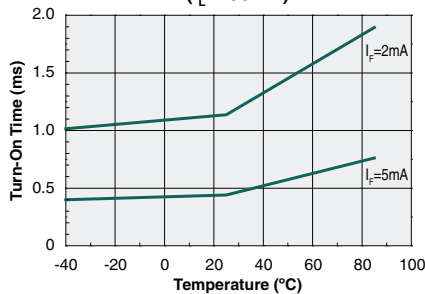
Typical Turn-Off Time  
vs. LED Forward Current  
( $I_L=100\text{mA}$ )



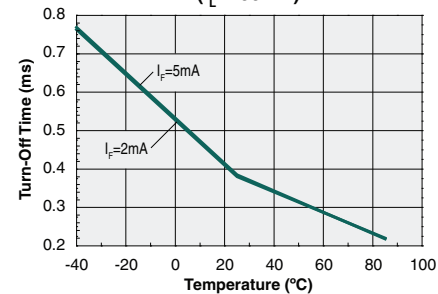
Typical LED Current to Operate  
vs. Temperature  
( $I_L=500\text{mA}$ )



Typical Turn-On Time vs. Temperature  
( $I_L=100\text{mA}$ )



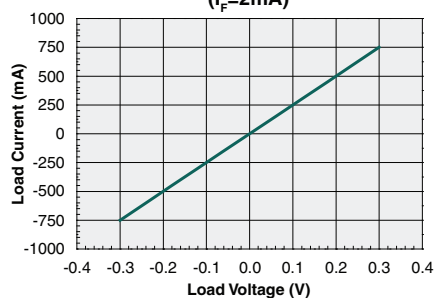
Typical Turn-Off Time vs. Temperature  
( $I_L=100\text{mA}$ )



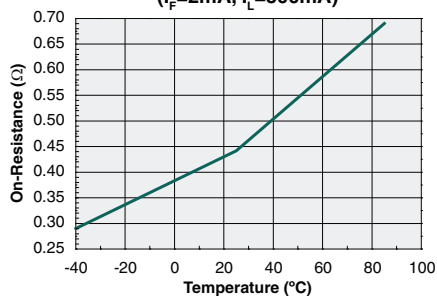
\*Unless otherwise noted, data presented in these graphs is typical of device operation at  $25^{\circ}\text{C}$ .

## PERFORMANCE DATA \*

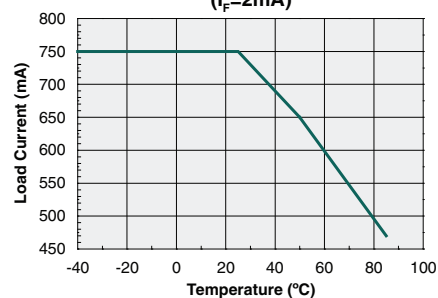
**Typical Load Current  
vs. Load Voltage  
( $I_F=2\text{mA}$ )**



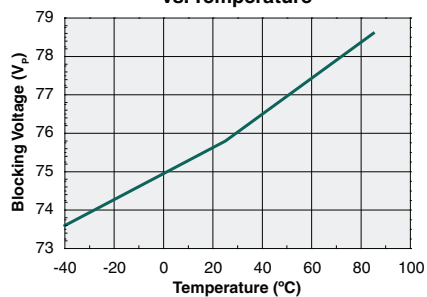
**Typical On-Resistance vs. Temperature  
( $I_F=2\text{mA}$ ,  $I_L=500\text{mA}$ )**



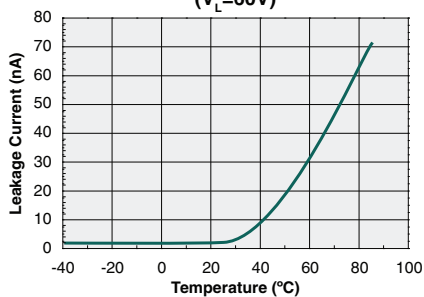
**Maximum Load Current  
vs. Temperature  
( $I_F=2\text{mA}$ )**



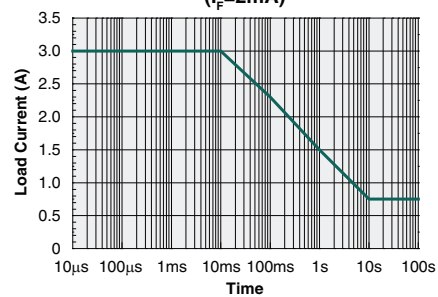
**Typical Blocking Voltage  
vs. Temperature**



**Typical Leakage Current  
vs. Temperature  
( $V_L=60\text{V}$ )**



**Energy Rating Curve  
( $I_F=2\text{mA}$ )**



\*Unless otherwise noted, data presented in these graphs is typical of device operation at 25 $^{\circ}\text{C}$ .

## Manufacturing Information

### Moisture Sensitivity



All plastic encapsulated semiconductor packages are susceptible to moisture ingress. IXYS Integrated Circuits classifies its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, **IPC/JEDEC J-STD-020**, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a **Moisture Sensitivity Level (MSL)** classification as shown below, and should be handled according to the requirements of the latest version of the joint industry standard **IPC/JEDEC J-STD-033**.

| Device   | Moisture Sensitivity Level (MSL) Classification |
|----------|-------------------------------------------------|
| CPC1019N | MSL 3                                           |

### ESD Sensitivity



This product is ESD Sensitive, and should be handled according to the industry standard **JESD-625**.

### Soldering Profile

Provided in the table below is the **IPC/JEDEC J-STD-020** Classification Temperature ( $T_C$ ) and the maximum dwell time the body temperature of these surface mount devices may be ( $T_C - 5$ )°C or greater. The Classification Temperature sets the Maximum Body Temperature allowed for these devices during reflow soldering processes.

| Device   | Classification Temperature ( $T_C$ ) | Dwell Time ( $t_p$ ) | Max Reflow Cycles |
|----------|--------------------------------------|----------------------|-------------------|
| CPC1019N | 260°C                                | 30 seconds           | 3                 |

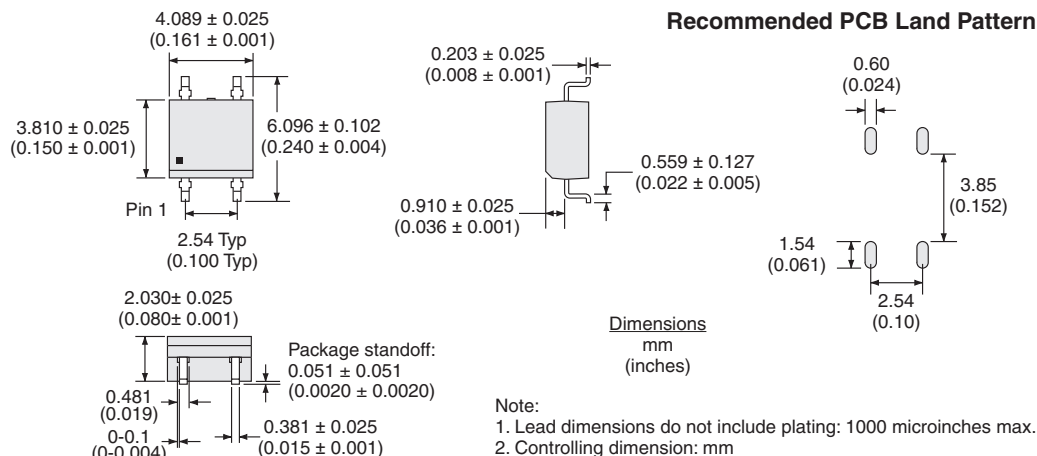
### Board Wash

IXYS Integrated Circuits recommends the use of no-clean flux formulations. Board washing to reduce or remove flux residue following the solder reflow process is acceptable provided proper precautions are taken to prevent damage to the device. These precautions include but are not limited to: using a low pressure wash and providing a follow up bake cycle sufficient to remove any moisture trapped within the device due to the washing process. Due to the variability of the wash parameters used to clean the board, determination of the bake temperature and duration necessary to remove the moisture trapped within the package is the responsibility of the user (assembler). Cleaning or drying methods that employ ultrasonic energy may damage the device and should not be used. Additionally, the device must not be exposed to halide flux or solvents.

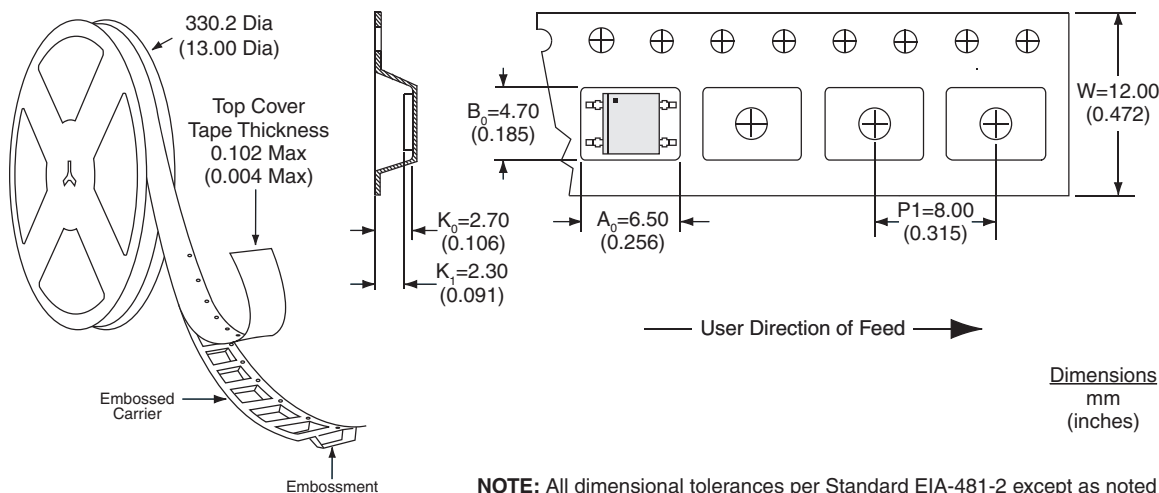


## MECHANICAL DIMENSIONS

### CPC1019N



### CPC1019NTR Tape & Reel



For additional information please visit our website at: <https://www.ixysic.com>